

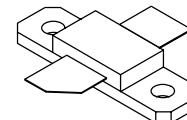
The RF Sub-Micron MOSFET Line
RF Power Field Effect Transistors
N-Channel Enhancement-Mode Lateral MOSFETs

Designed for broadband commercial and industrial applications with frequencies up to 1.0 GHz. The high gain and broadband performance of these devices make them ideal for large-signal, common-source amplifier applications in 28 volt base station equipment.

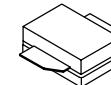
- Typical Two-Tone Performance at 945 MHz, 28 Volts
 - Output Power — 45 Watts PEP
 - Power Gain — 18.8 dB
 - Efficiency — 42%
 - IMD — -32 dBc
- Integrated ESD Protection
- Designed for Maximum Gain and Insertion Phase Flatness
- Capable of Handling 10:1 VSWR, @ 28 Vdc, 945 MHz, 45 Watts CW Output Power
- Excellent Thermal Stability
- Characterized with Series Equivalent Large-Signal Impedance Parameters
- In Tape and Reel. R1 Suffix = 500 Units per 32 mm, 13 inch Reel.
- Low Gold Plating Thickness on Leads. L Suffix Indicates 40 μ " Nominal.

MRF9045LR1
MRF9045LSR1

945 MHz, 45 W, 28 V
 LATERAL N-CHANNEL
 BROADBAND
 RF POWER MOSFETs



CASE 360B-05, STYLE 1
 NI-360
 MRF9045LR1



CASE 360C-05, STYLE 1
 NI-360S
 MRF9045LSR1

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	65	Vdc
Gate-Source Voltage	V _{GS}	- 0.5, + 15	Vdc
Total Device Dissipation @ T _C = 25°C Derate above 25°C	P _D	125 0.71 175 1	Watts W/°C
Storage Temperature Range	T _{stg}	- 65 to +150	°C
Operating Junction Temperature	T _J	200	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	R _{θJC}	1.4 1.0	°C/W

ESD PROTECTION CHARACTERISTICS

Test Conditions	Class
Human Body Model	1 (Minimum)
Machine Model	M1 (Minimum)

NOTE - **CAUTION** - MOS devices are susceptible to damage from electrostatic charge. Reasonable precautions in handling and packaging MOS devices should be observed.

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ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Zero Gate Voltage Drain Leakage Current ($V_{DS} = 65 \text{ Vdc}$, $V_{GS} = 0 \text{ Vdc}$)	I_{DSS}	—	—	10	μAdc
Zero Gate Voltage Drain Leakage Current ($V_{DS} = 28 \text{ Vdc}$, $V_{GS} = 0 \text{ Vdc}$)	I_{DSS}	—	—	1	μAdc
Gate-Source Leakage Current ($V_{GS} = 5 \text{ Vdc}$, $V_{DS} = 0 \text{ Vdc}$)	I_{GSS}	—	—	1	μAdc
ON CHARACTERISTICS					
Gate Threshold Voltage ($V_{DS} = 10 \text{ Vdc}$, $I_D = 150 \mu\text{Adc}$)	$V_{GS(\text{th})}$	2	3	4	Vdc
Gate Quiescent Voltage ($V_{DS} = 28 \text{ Vdc}$, $I_D = 350 \text{ mAdc}$)	$V_{GS(Q)}$	—	3.7	—	Vdc
Drain-Source On-Voltage ($V_{GS} = 10 \text{ Vdc}$, $I_D = 1 \text{ Adc}$)	$V_{DS(\text{on})}$	—	0.19	0.4	Vdc
Forward Transconductance ($V_{DS} = 10 \text{ Vdc}$, $I_D = 3 \text{ Adc}$)	g_{fs}	—	4	—	S
DYNAMIC CHARACTERISTICS					
Input Capacitance ($V_{DS} = 28 \text{ Vdc} \pm 30 \text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0 \text{ Vdc}$)	C_{iss}	—	69	—	pF
Output Capacitance ($V_{DS} = 28 \text{ Vdc} \pm 30 \text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0 \text{ Vdc}$)	C_{oss}	—	37	—	pF
Reverse Transfer Capacitance ($V_{DS} = 28 \text{ Vdc} \pm 30 \text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0 \text{ Vdc}$)	C_{rss}	—	1.5	—	pF

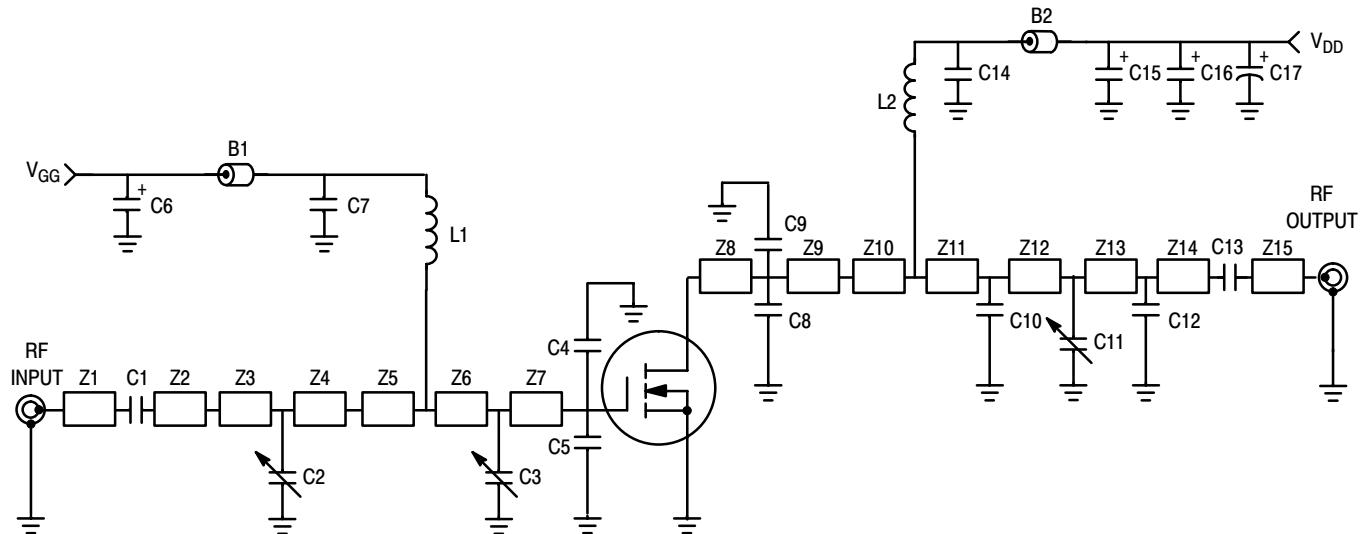
(continued)

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ELECTRICAL CHARACTERISTICS — continued ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
FUNCTIONAL TESTS (In Motorola Test Fixture, 50 ohm system)					
Two-Tone Common-Source Amplifier Power Gain ($V_{DD} = 28 \text{ Vdc}$, $P_{out} = 45 \text{ W PEP}$, $I_{DQ} = 350 \text{ mA}$, $f_1 = 945.0 \text{ MHz}$, $f_2 = 945.1 \text{ MHz}$)	G_{ps}	17	18.8	—	dB
Two-Tone Drain Efficiency ($V_{DD} = 28 \text{ Vdc}$, $P_{out} = 45 \text{ W PEP}$, $I_{DQ} = 350 \text{ mA}$, $f_1 = 945.0 \text{ MHz}$, $f_2 = 945.1 \text{ MHz}$)	η	38	42	—	%
3rd Order Intermodulation Distortion ($V_{DD} = 28 \text{ Vdc}$, $P_{out} = 45 \text{ W PEP}$, $I_{DQ} = 350 \text{ mA}$, $f_1 = 945.0 \text{ MHz}$, $f_2 = 945.1 \text{ MHz}$)	IMD	—	-32	-28	dBc
Input Return Loss ($V_{DD} = 28 \text{ Vdc}$, $P_{out} = 45 \text{ W PEP}$, $I_{DQ} = 350 \text{ mA}$, $f_1 = 945.0 \text{ MHz}$, $f_2 = 945.1 \text{ MHz}$)	IRL	—	-14	-9	dB
Two-Tone Common-Source Amplifier Power Gain ($V_{DD} = 28 \text{ Vdc}$, $P_{out} = 45 \text{ W PEP}$, $I_{DQ} = 350 \text{ mA}$, $f_1 = 930.0 \text{ MHz}$, $f_2 = 930.1 \text{ MHz}$ and $f_1 = 960.0 \text{ MHz}$, $f_2 = 960.1 \text{ MHz}$)	G_{ps}	—	18.5	—	dB
Two-Tone Drain Efficiency ($V_{DD} = 28 \text{ Vdc}$, $P_{out} = 45 \text{ W PEP}$, $I_{DQ} = 350 \text{ mA}$, $f_1 = 930.0 \text{ MHz}$, $f_2 = 930.1 \text{ MHz}$ and $f_1 = 960.0 \text{ MHz}$, $f_2 = 960.1 \text{ MHz}$)	η	—	41	—	%
3rd Order Intermodulation Distortion ($V_{DD} = 28 \text{ Vdc}$, $P_{out} = 45 \text{ W PEP}$, $I_{DQ} = 350 \text{ mA}$, $f_1 = 930.0 \text{ MHz}$, $f_2 = 930.1 \text{ MHz}$ and $f_1 = 960.0 \text{ MHz}$, $f_2 = 960.1 \text{ MHz}$)	IMD	—	-33	—	dBc
Input Return Loss ($V_{DD} = 28 \text{ Vdc}$, $P_{out} = 45 \text{ W PEP}$, $I_{DQ} = 350 \text{ mA}$, $f_1 = 930.0 \text{ MHz}$, $f_2 = 930.1 \text{ MHz}$ and $f_1 = 960.0 \text{ MHz}$, $f_2 = 960.1 \text{ MHz}$)	IRL	—	13	—	dB
Power Output, 1 dB Compression Point ($V_{DD} = 28 \text{ Vdc}$, $P_{out} = 45 \text{ W CW}$, $I_{DQ} = 350 \text{ mA}$, $f_1 = 945.0 \text{ MHz}$)	$P_{1\text{dB}}$	—	55	—	W
Common-Source Amplifier Power Gain ($V_{DD} = 28 \text{ Vdc}$, $P_{out} = 45 \text{ W CW}$, $I_{DQ} = 350 \text{ mA}$, $f_1 = 945.0 \text{ MHz}$)	G_{ps}	—	18	—	dB
Drain Efficiency ($V_{DD} = 28 \text{ Vdc}$, $P_{out} = 45 \text{ W CW}$, $I_{DQ} = 350 \text{ mA}$, $f_1 = 945.0 \text{ MHz}$)	η	—	60	—	%
Output Mismatch Stress ($V_{DD} = 28 \text{ Vdc}$, $P_{out} = 45 \text{ W CW}$, $I_{DQ} = 350 \text{ mA}$, $f = 945.0 \text{ MHz}$, $\text{VSWR} = 10:1$, All Phase Angles at Frequency of Tests)	Ψ	No Degradation In Output Power			

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B1	Short Ferrite Bead Surface Mount
B2	Long Ferrite Bead Surface Mount
C1, C7, C13, C14	47 pF Chip Capacitors, B Case
C2, C3, C11	0.8-8.0 pF Gigatrilm Variable Trim Capacitors
C4, C5, C8, C9	10 pF Chip Capacitors, B Case
C6, C15, C16	10 µF, 35 V Tantalum Surface Mount Chip Capacitors
C10	2.2 pF Chip Capacitor, B Case
C12	0.7 pF Chip Capacitor, B Case - MRF9045
C17	1.3 pF Chip Capacitor, B Case - MRF9045
L1, L2	220 µF, 50 V Electrolytic Capacitor
Z1	12.5 nH Surface Mount Inductors, Coilcraft
Z2	0.260" x 0.080" Microstrip
Z3	0.610" x 0.120" Microstrip
Z4	0.360" x 0.320" Microstrip
Z5	0.240" x 0.320" x 0.620", Taper
Z6	0.140" x 0.620" Microstrip
Z7	0.510" x 0.620" Microstrip
Z8	0.330" x 0.320" Microstrip
Z9	0.140" x 0.320" Microstrip
Z10	0.070" x 0.080" Microstrip
Z11	0.240" x 0.080" Microstrip
Z12	0.140" x 0.080" Microstrip
Z13	0.930" x 0.080" Microstrip
Z14	0.180" x 0.080" Microstrip
Z15	0.350" x 0.080" Microstrip
PCB	Arlon GX-0300-55-22, 0.03", $\epsilon_r = 2.55$

Figure 1. 930 - 960 MHz Broadband Test Circuit Schematic

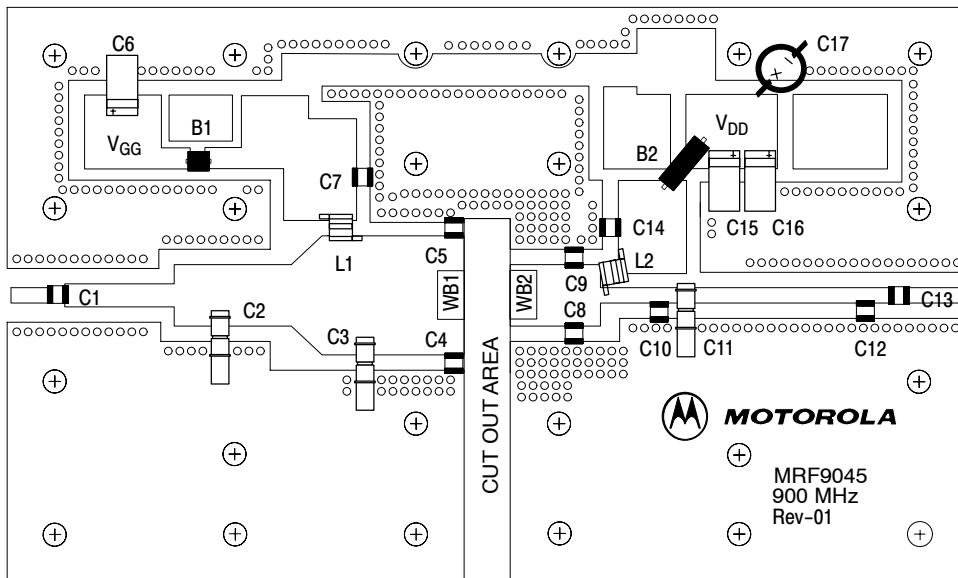


Figure 2. 930 - 960 MHz Broadband Test Circuit Component Layout

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TYPICAL CHARACTERISTICS

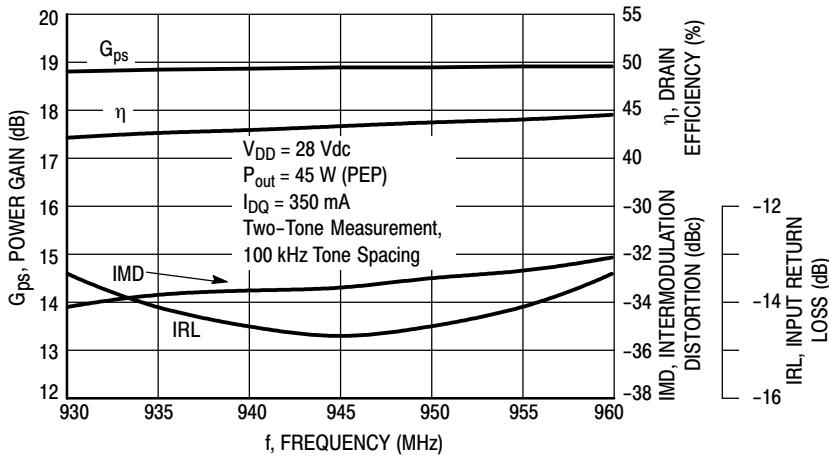


Figure 3. Class AB Broadband Circuit Performance

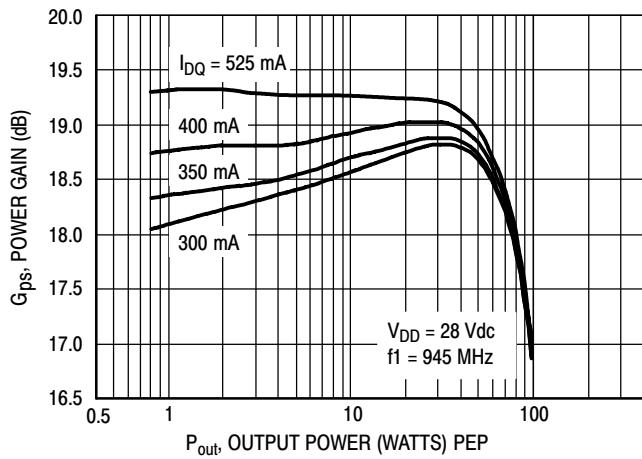


Figure 4. Power Gain versus Output Power

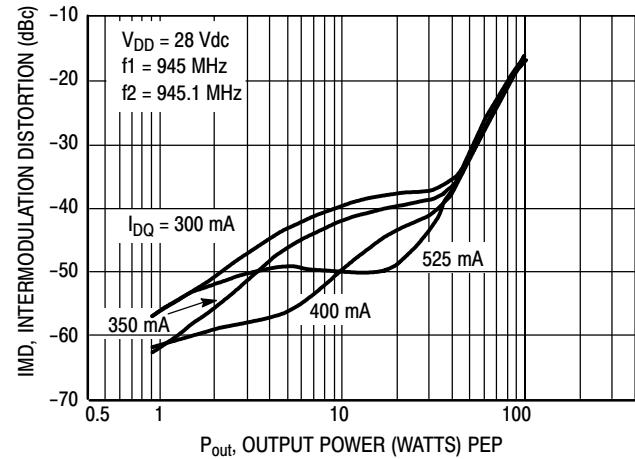


Figure 5. Intermodulation Distortion versus Output Power

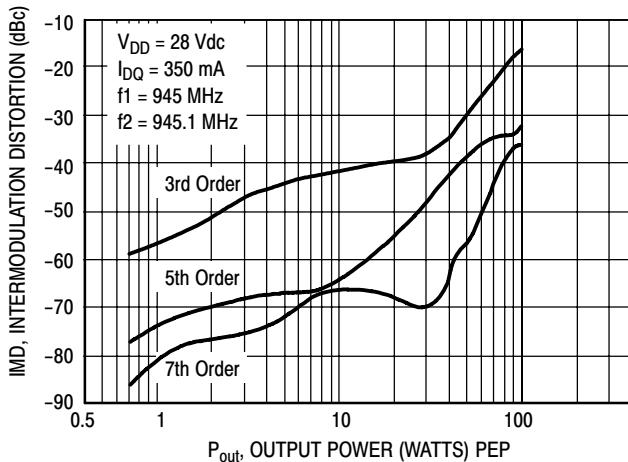


Figure 6. Intermodulation Distortion Products versus Output Power

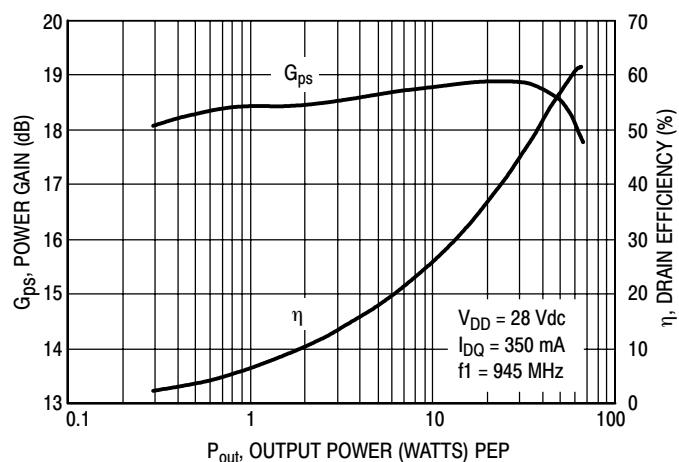
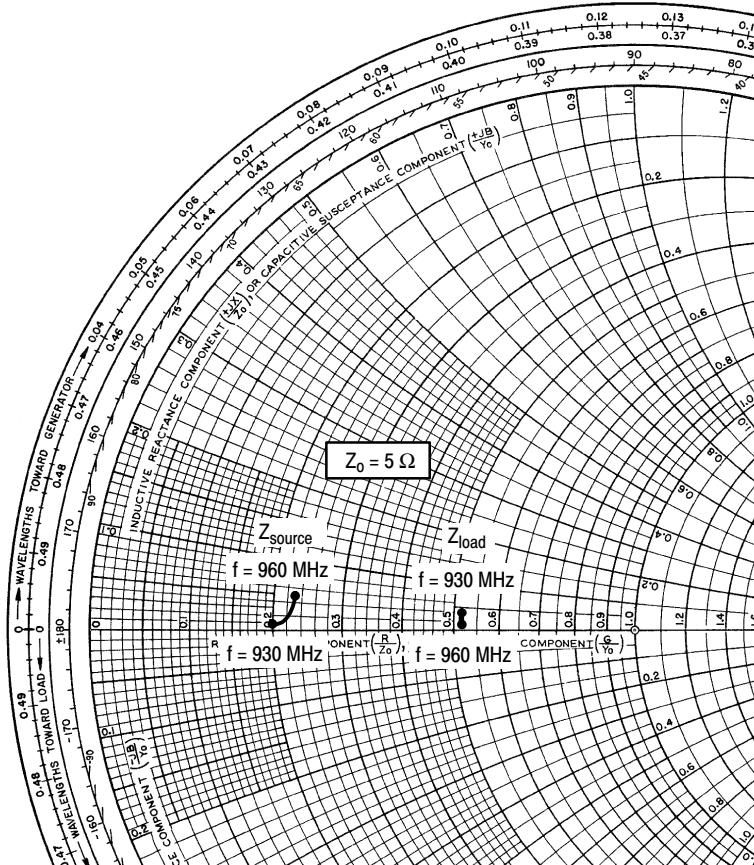


Figure 7. Power Gain, Efficiency versus Output Power



$V_{DD} = 28$ V, $I_{DQ} = 350$ mA, $P_{out} = 45$ W PEP

f MHz	Z_{source} Ω	Z_{load} Ω
930	$1.02 + j0.06$	$2.6 + j0.20$
945	$1.10 + j0.11$	$2.6 + j0.16$
960	$1.15 + j0.25$	$2.6 + j0.10$

Z_{source} = Test circuit impedance as measured from gate to ground.

Z_{load} = Test circuit impedance as measured from drain to ground.

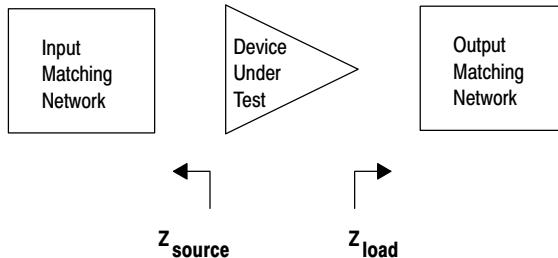
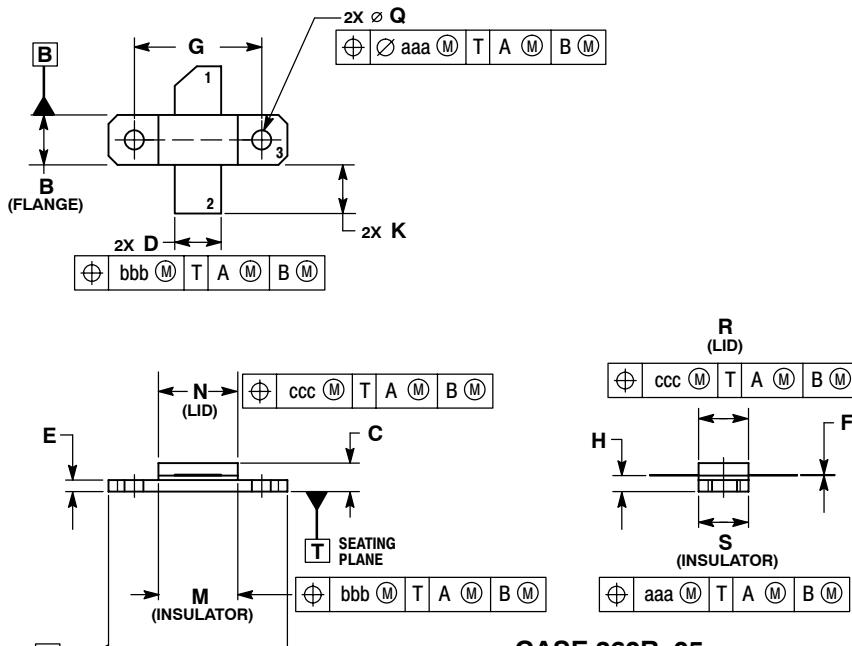


Figure 8. Series Equivalent Input and Output Impedance

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PACKAGE DIMENSIONS

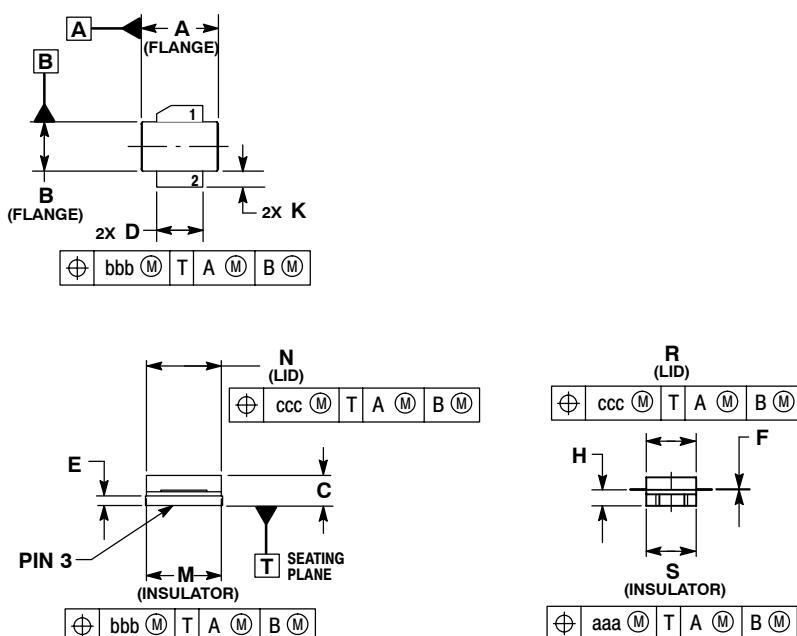


NOTES:

1. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION H IS MEASURED 0.030 (0.762) AWAY FROM PACKAGE BODY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.795	0.805	20.19	20.45
B	0.225	0.235	5.72	5.97
C	0.125	0.175	3.18	4.45
D	0.210	0.220	5.33	5.59
E	0.055	0.065	1.40	1.65
F	0.004	0.006	0.10	0.15
G	0.562	BSC	14.28	BSC
H	0.077	0.087	1.96	2.21
K	0.220	0.250	5.59	6.35
M	0.355	0.365	9.02	9.27
N	0.357	0.363	9.07	9.22
Q	0.125	0.135	3.18	3.43
R	0.227	0.233	5.77	5.92
S	0.225	0.235	5.72	5.97
aaa	0.005	REF	0.13	REF
bbb	0.010	REF	0.25	REF
ccc	0.015	REF	0.38	REF

STYLE 1:
PIN 1. DRAIN
2. GATE
3. SOURCE



NOTES:

1. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
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DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.375	0.385	9.53	9.78
B	0.225	0.235	5.72	5.97
C	0.105	0.155	2.67	3.94
D	0.210	0.220	5.33	5.59
E	0.035	0.045	0.89	1.14
F	0.004	0.006	0.10	0.15
H	0.057	0.067	1.45	1.70
K	0.085	0.115	2.16	2.92
M	0.355	0.365	9.02	9.27
N	0.357	0.363	9.07	9.22
R	0.227	0.23	5.77	5.92
S	0.225	0.235	5.72	5.97
aaa	0.005	REF	0.13	REF
bbb	0.010	REF	0.25	REF
ccc	0.015	REF	0.38	REF

STYLE 1:
PIN 1. DRAIN
2. GATE
3. SOURCE

**CASE 360C-05
ISSUE D
NI-360S
MRF9045LSR1**

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MRF9045/D